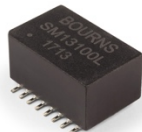


MATERIAL DECLARATION SHEET



Material Number	SM13100EL			
Product Line	LAN Transformer			
Compliance Date	2017-10-11			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	MnZn ferrite core	0.28	Iron oxide	1309-37-1	55	2.8149	5.1180
				Zinc oxide	1314-13-2	25	1.2795	
				Manganese oxide	1344-43-0	20	1.0236	
		NiZn ferrite core	0.055	Iron oxide	1309-37-1	50	0.5026	1.0053
				Zinc oxide	1314-13-2	15	0.1508	
				Nickel oxide	1313-99-1	35	0.3518	
2	Enameled Copper Wire	Enameled Copper Wire	0.066	Copper	7440-50-8	87.5	1.0556	1.2064
				Polyurethane resin	9009-54-5	11.9	0.1436	
				Polyamide resin	32131-17-2	0.6	0.0072	
3	PFA180 Supplementary insulation wire	PFA180 Supplementary insulation wire	0.147	Polytetrafluoroethylene-co-perfluoro(alkyl vinyl ether)	26655-00-5	100	2.6869	2.6869
		Tinned copper wire	0.013	Copper	7440-50-8	70	0.16632	0.2376
				Tin	7440-31-5	30	0.07128	
4	Case	Diallyl Phthalate (DAP) Molding Compound	3.24	DAP resin	25035-78-3	25	14.8053	59.2213
				Aluminum Trihydroxide	21645-51-2	45	26.6496	
				Glass Fiber	65997-17-3	30	17.7664	
5	Terminal PIN	Phosphor Bronze Alloys	0.207	Copper	7440-50-8	89.5	3.3863	3.7836
				Nickel	7440-02-0	1.5	0.0567	
				Tin	7440-31-5	9	0.3405	
6	Silicon	Silicon	1.374	Poly(dimethylsiloxane), vinyl terminated	68083-19-2	65	16.3242	25.1142
				Silicon dioxide	14808-60-7	33	8.2877	
				Carbon Black	1333-86-4	1	0.2511	
				1,3-Divinyltetramethyldi-siloxane complex	68478-92-2	1	0.2511	
7	Double side tape	Double side tape	0.03	Acrylate Adhesive Copolymer	-	60	0.32898	0.5483
				Paper Liner	-	40	0.21932	

MATERIAL DECLARATION SHEET



8	Pin Solder	Sn100	0.035	Tin	7440-31-5	100	0.6397	0.6397
9	Inner Pin Solder	Sn96/Cu4	0.024	Tin	7440-31-5	96	0.421152	0.4387
				Copper	7440-50-8	4	0.017548	
		Total weight	5.471					

This Document was updated on: 2017-10-11